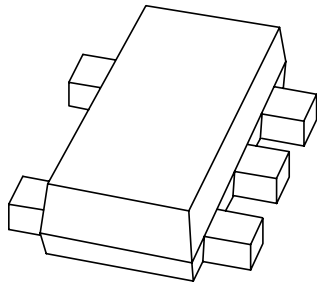


DATA SHEET



BZA900AVL series Quadruple low capacitance ESD suppressor

Product data sheet
Supersedes data of 2003 Apr 15

2003 Oct 20



Quadruple low capacitance ESD suppressor

BZA900AVL series

FEATURES

- Low diode capacitance
- Low leakage current
- SOT665 surface mount package
- Common anode configuration.

APPLICATIONS

- Communication systems
- Computers and peripherals
- Audio and video equipment.

DESCRIPTION

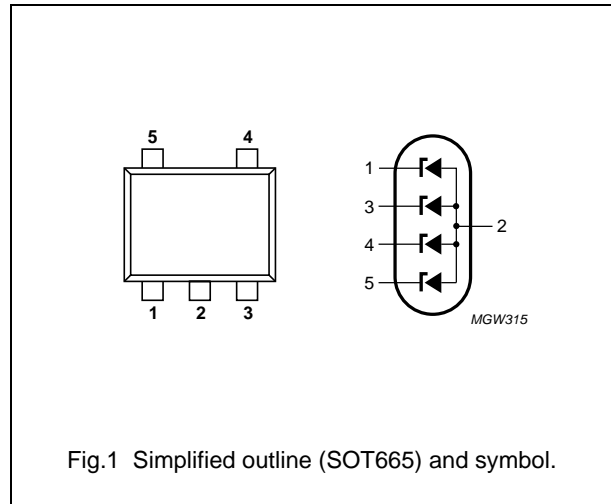
Monolithic transient voltage suppressor diode in a five lead SOT665 package for 4-bit wide ESD transient suppression.

MARKING

| TYPE NUMBER | MARKING CODE |
|-------------|--------------|
| BZA956AVL | V3 |
| BZA962AVL | V2 |
| BZA968AVL | V1 |

PINNING

| PIN | DESCRIPTION |
|-----|--------------|
| 1 | cathode 1 |
| 2 | common anode |
| 3 | cathode 2 |
| 4 | cathode 3 |
| 5 | cathode 4 |



ORDERING INFORMATION

| TYPE NUMBER | PACKAGE | | |
|-------------|---------|--|---------|
| | NAME | DESCRIPTION | VERSION |
| BZA956AVL | – | plastic surface mounted package; 5 leads | SOT665 |
| BZA962AVL | – | plastic surface mounted package; 5 leads | SOT665 |
| BZA968AVL | – | plastic surface mounted package; 5 leads | SOT665 |

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

| SYMBOL | PARAMETER | CONDITIONS | MIN. | MAX. | UNIT |
|------------------|---|--|------|--------|------|
| Per diode | | | | | |
| I_Z | working current | $T_{amb} = 25\text{ °C}$ | – | note 1 | mA |
| I_F | continuous forward current | $T_{amb} = 25\text{ °C}$ | – | 200 | mA |
| I_{FSM} | non-repetitive peak forward current | $t_p = 1\text{ ms}$; square pulse | – | 3.5 | A |
| P_{tot} | total power dissipation | $T_{amb} = 25\text{ °C}$; note 2; see Fig.5 | – | 335 | mW |
| P_{ZSM} | non repetitive peak reverse power dissipation | square pulse; $t_p = 1\text{ ms}$ | – | 6 | W |
| T_{stg} | storage temperature | | –65 | +150 | °C |
| T_j | junction temperature | | – | 150 | °C |
| ESD | electrostatic discharge | IEC 61000-4-2 (contact discharge) | 15 | – | kV |
| | | HBM MIL-Std 883 | 10 | – | kV |

Notes

- DC working current limited by $P_{tot(max)}$.
- Device mounted on standard printed-circuit board.

ESD STANDARDS COMPLIANCE

| STANDARD | CONDITIONS |
|------------------------------|---|
| IEC 61000-4-2, level 4 (ESD) | >15 kV (air); >8 kV (contact discharge) |
| HBM MIL-Std 883, class 3 | >4 kV |

THERMAL CHARACTERISTICS

| SYMBOL | PARAMETER | CONDITIONS | VALUE | UNIT |
|---------------|--|-------------------|-------|------|
| $R_{th\ j-a}$ | thermal resistance from junction to ambient | all diodes loaded | 370 | K/W |
| $R_{th\ j-s}$ | thermal resistance from junction to solder point; note 1 | one diode loaded | 135 | K/W |
| | | all diodes loaded | 125 | K/W |

Note

- Solder point of common anode (pin 2).

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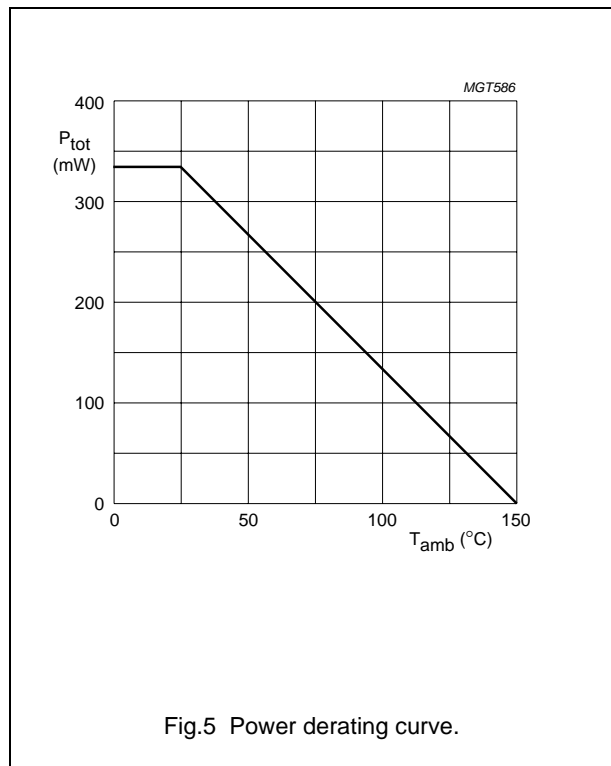
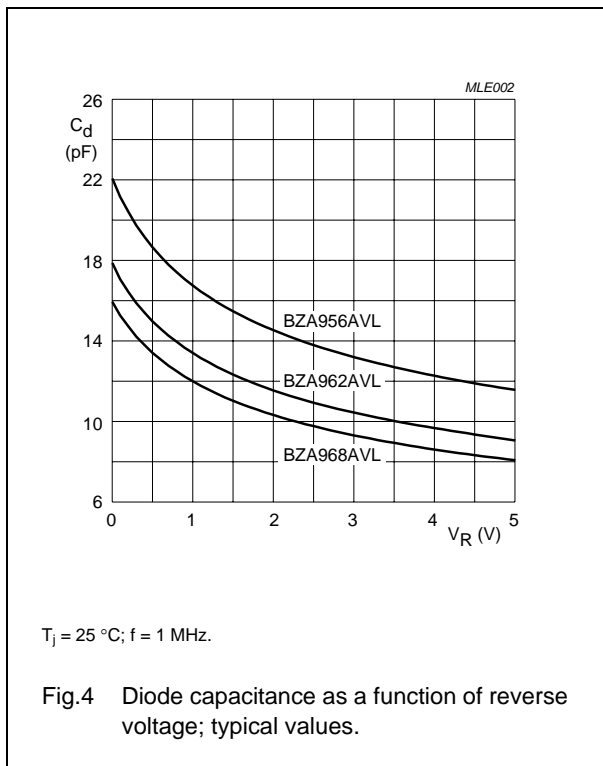
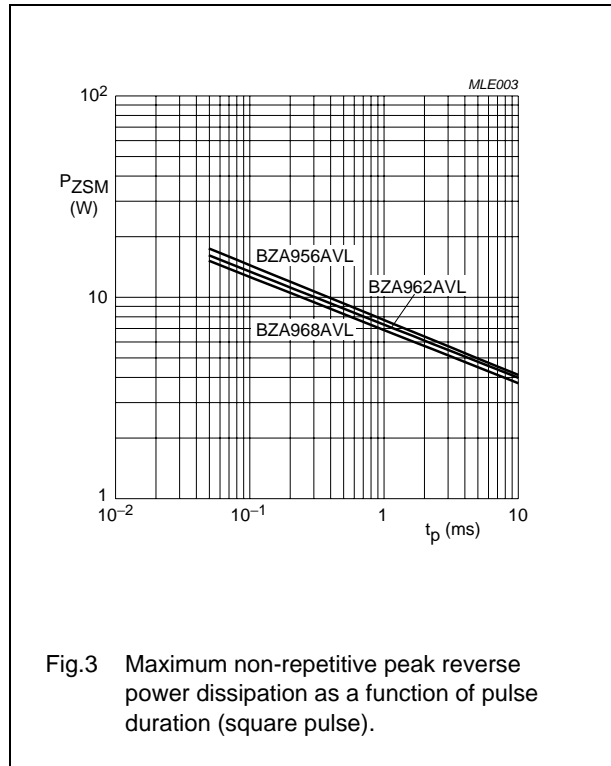
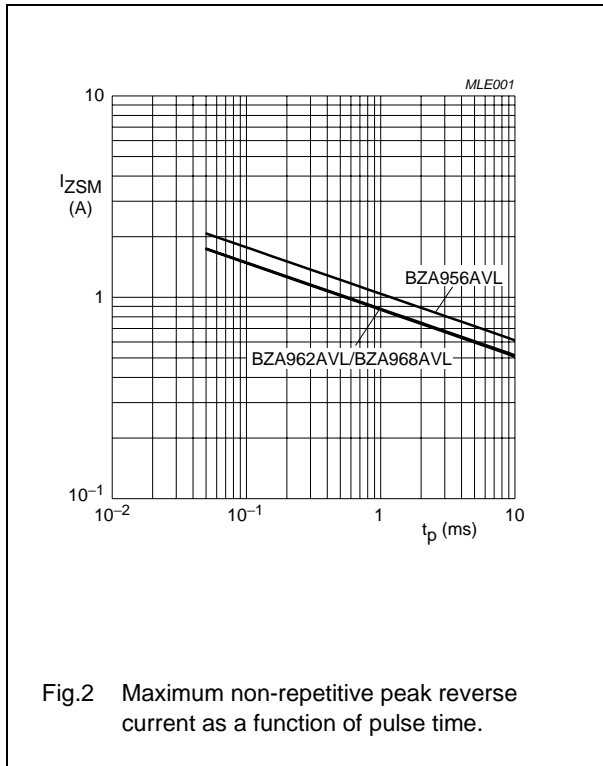
ELECTRICAL CHARACTERISTICS

$T_j = 25\text{ °C}$ unless otherwise specified.

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|-----------|-------------------------------------|---|------|------|------|----------|
| V_F | forward voltage | $I_F = 200\text{ mA}$ | – | – | 1.2 | V |
| I_R | reverse current | | | | | |
| | BZA956AVL | $V_R = 3\text{ V}$ | – | – | 200 | nA |
| | BZA962AVL | $V_R = 4\text{ V}$ | – | – | 100 | nA |
| | BZA968AVL | $V_R = 4.3\text{ V}$ | – | – | 20 | nA |
| V_Z | working voltage | $I_Z = 1\text{ mA}$ | | | | |
| | BZA956AVL | | 5.32 | 5.6 | 5.88 | V |
| | BZA962AVL | | 5.89 | 6.2 | 6.51 | V |
| | BZA968AVL | | 6.46 | 6.8 | 7.14 | V |
| r_{dif} | differential resistance | $I_Z = 1\text{ mA}$ | | | | |
| | BZA956AVL | | – | – | 200 | Ω |
| | BZA962AVL | | – | – | 150 | Ω |
| | BZA968AVL | | – | – | 100 | Ω |
| S_Z | temperature coefficient | $I_Z = 1\text{ mA}$ | | | | |
| | BZA956AVL | | – | 1.3 | – | mV/K |
| | BZA962AVL | | – | 2.4 | – | mV/K |
| | BZA968AVL | | – | 2.9 | – | mV/K |
| C_d | diode capacitance | $f = 1\text{ MHz}; V_R = 0$ | | | | |
| | BZA956AVL | | – | 22 | 28 | pF |
| | BZA962AVL | | – | 18 | 22 | pF |
| | BZA968AVL | | – | 16 | 19 | pF |
| | diode capacitance | $f = 1\text{ MHz}; V_R = 5\text{ V}$ | | | | |
| | BZA956AVL | | – | 12 | 17 | pF |
| | BZA962AVL | | – | 9 | 12 | pF |
| | BZA968AVL | | – | 8 | 11 | pF |
| I_{ZSM} | non-repetitive peak reverse current | $t_p = 1\text{ ms}; T_{amb} = 25\text{ °C}$ | | | | |
| | BZA956AVL | | – | – | 0.90 | A |
| | BZA962AVL | | – | – | 0.85 | A |
| | BZA968AVL | | – | – | 0.80 | A |

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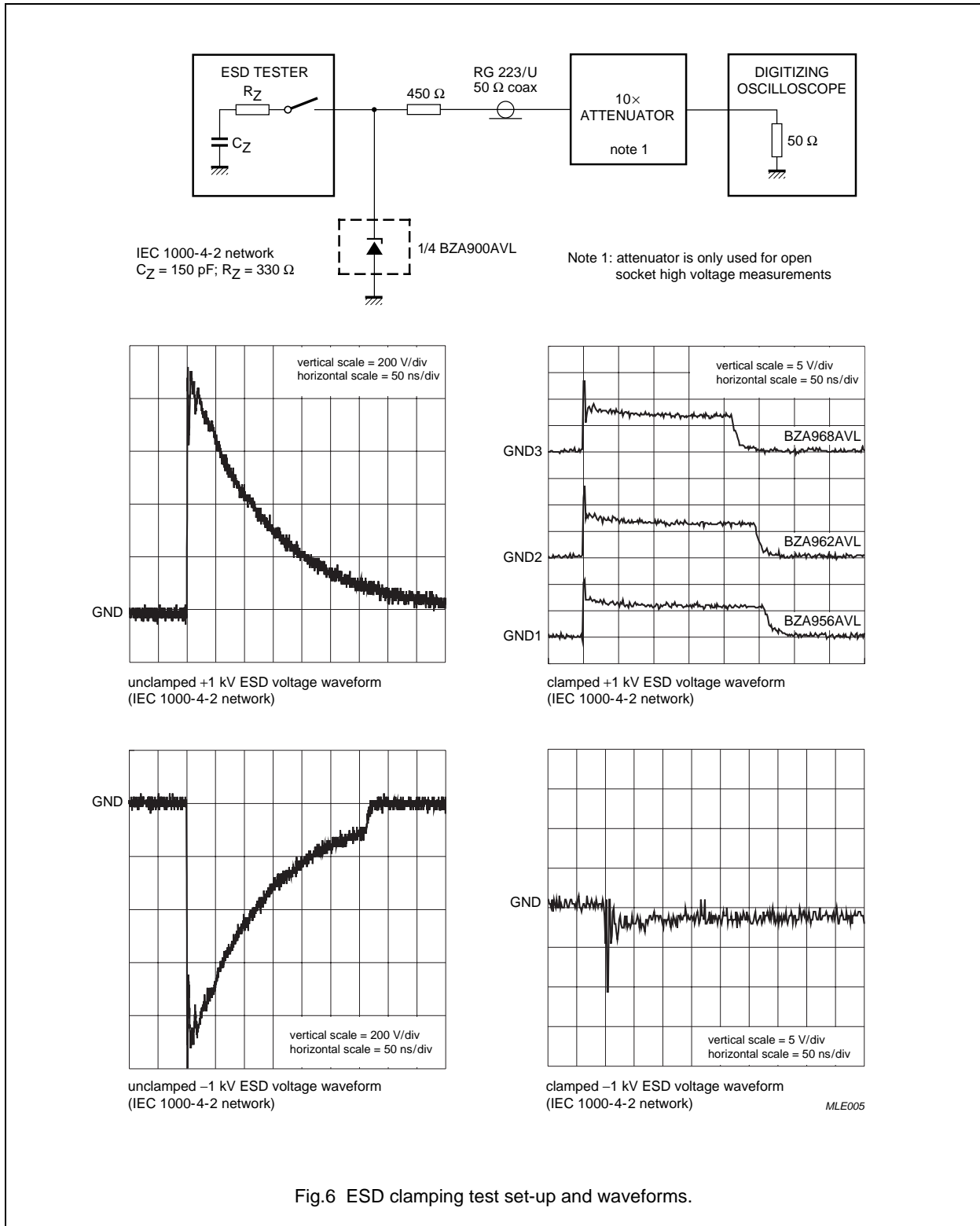


Fig.6 ESD clamping test set-up and waveforms.

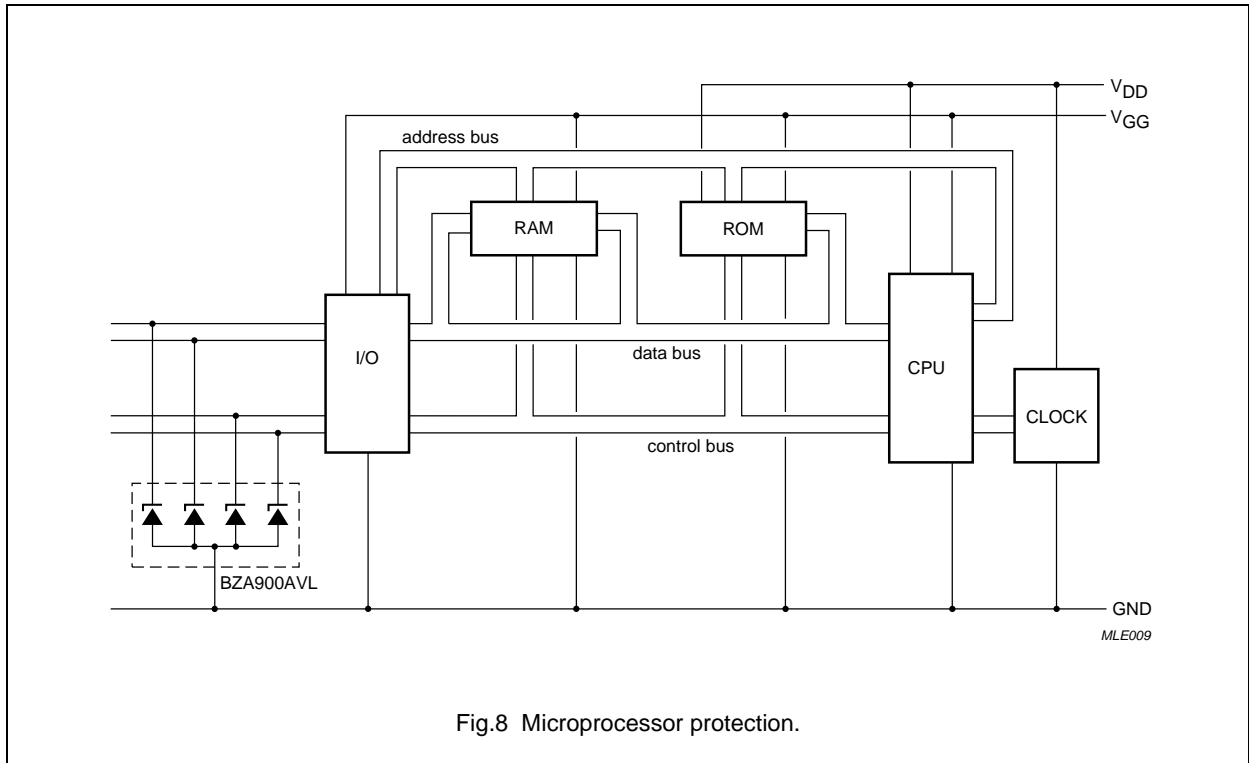
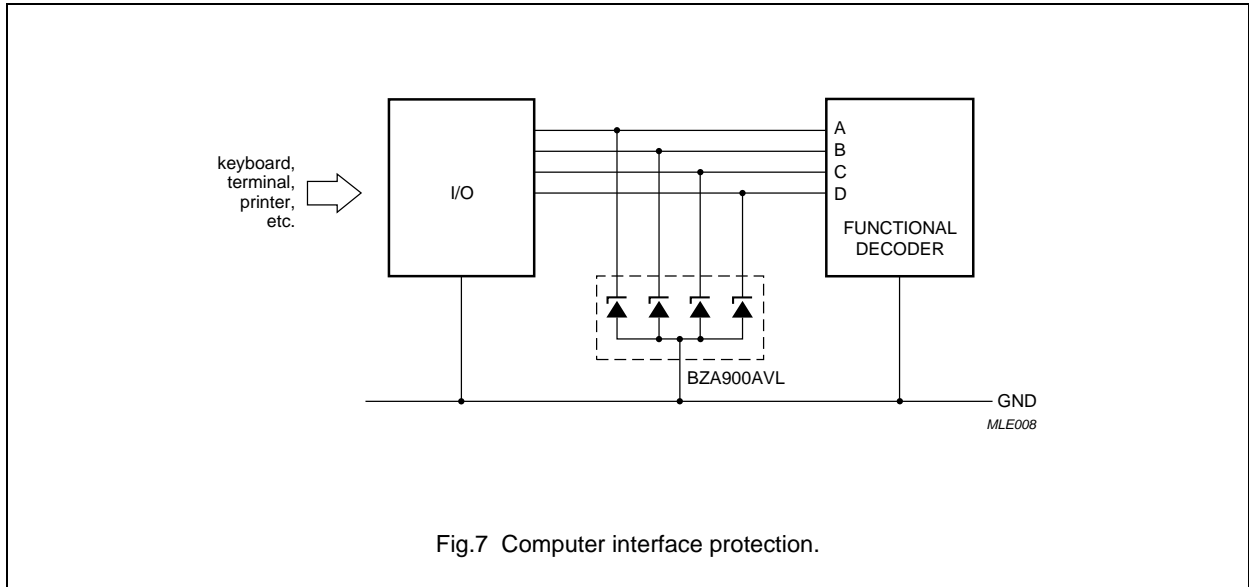
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APPLICATION INFORMATION

Typical common anode application

A quadruple transient suppressor in a SOT665 package makes it possible to protect four separate lines using only one package. Two simplified examples are shown in Figs.7 and 8.



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Device placement and printed-circuit board layout

Circuit board layout is of extreme importance in the suppression of transients. The clamping voltage of the BZA900AVL is determined by the peak transient current and the rate of rise of that current (di/dt). Since parasitic inductances can further add to the clamping voltage ($V = L di/dt$) the series conductor lengths on the printed-circuit board should be kept to a minimum. This includes the lead length of the suppression element.

In addition to minimizing conductor length the following printed-circuit board layout guidelines are recommended:

1. Place the suppression element close to the input terminals or connectors
2. Keep parallel signal paths to a minimum
3. Avoid running protection conductors in parallel with unprotected conductors
4. Minimize all printed-circuit board loop areas including power and ground loops
5. Minimize the length of the transient return path to ground
6. Avoid using shared transient return paths to a common ground point.

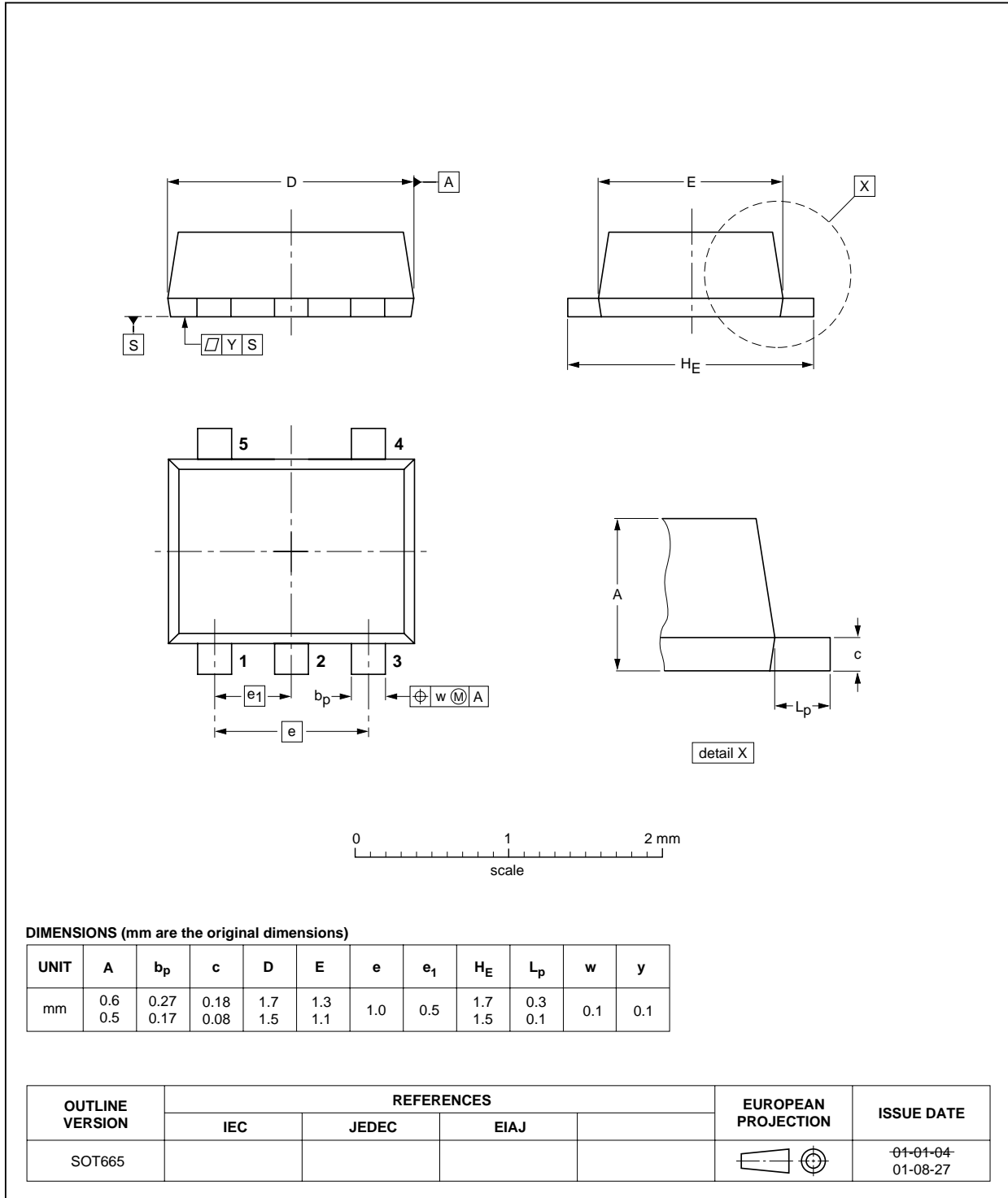
Quadruple low capacitance ESD suppressor

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PACKAGE OUTLINE

Plastic surface mounted package; 5 leads

SOT665



Quadruple low capacitance ESD suppressor

BZA900AVL series

DATA SHEET STATUS

| DOCUMENT STATUS ⁽¹⁾ | PRODUCT STATUS ⁽²⁾ | DEFINITION |
|--------------------------------|-------------------------------|---|
| Objective data sheet | Development | This document contains data from the objective specification for product development. |
| Preliminary data sheet | Qualification | This document contains data from the preliminary specification. |
| Product data sheet | Production | This document contains the product specification. |

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Printed in The Netherlands

R76/03/pp11

Date of release: 2003 Oct 20

Document order number: 9397 750 11935

